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United States Patent [19]

Nakayama et al.

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[45] **Date of Patent: **Aug. 11, 1998**

[54] **SEMICONDUCTOR DEVICE**

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[73] Assignee: **Matsushita Electronics Corporation**, Osaka, Japan

[**] Term: **14 Years**

[21] Appl. No.: **69,444**

[22] Filed: **Apr. 16, 1997**

[51] **LOC (6) Cl.** **13-03**

[52] **U.S. Cl.** **D13/182**

[58] **Field of Search** D13/182; 174/52.4, 174/52.5; 257/690; 361/752, 798, 820

[56] **References Cited**

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[57] **CLAIM**

The ornamental design for a semiconductor device, as shown.

DESCRIPTION

FIG. 1 is a perspective view of the top, front and left side of a semiconductor device showing our new design;

FIG. 2 is a perspective view of the bottom, rear and right side thereof;

FIG. 3 is a front elevational view thereof;

FIG. 4 is a top plan view thereof;

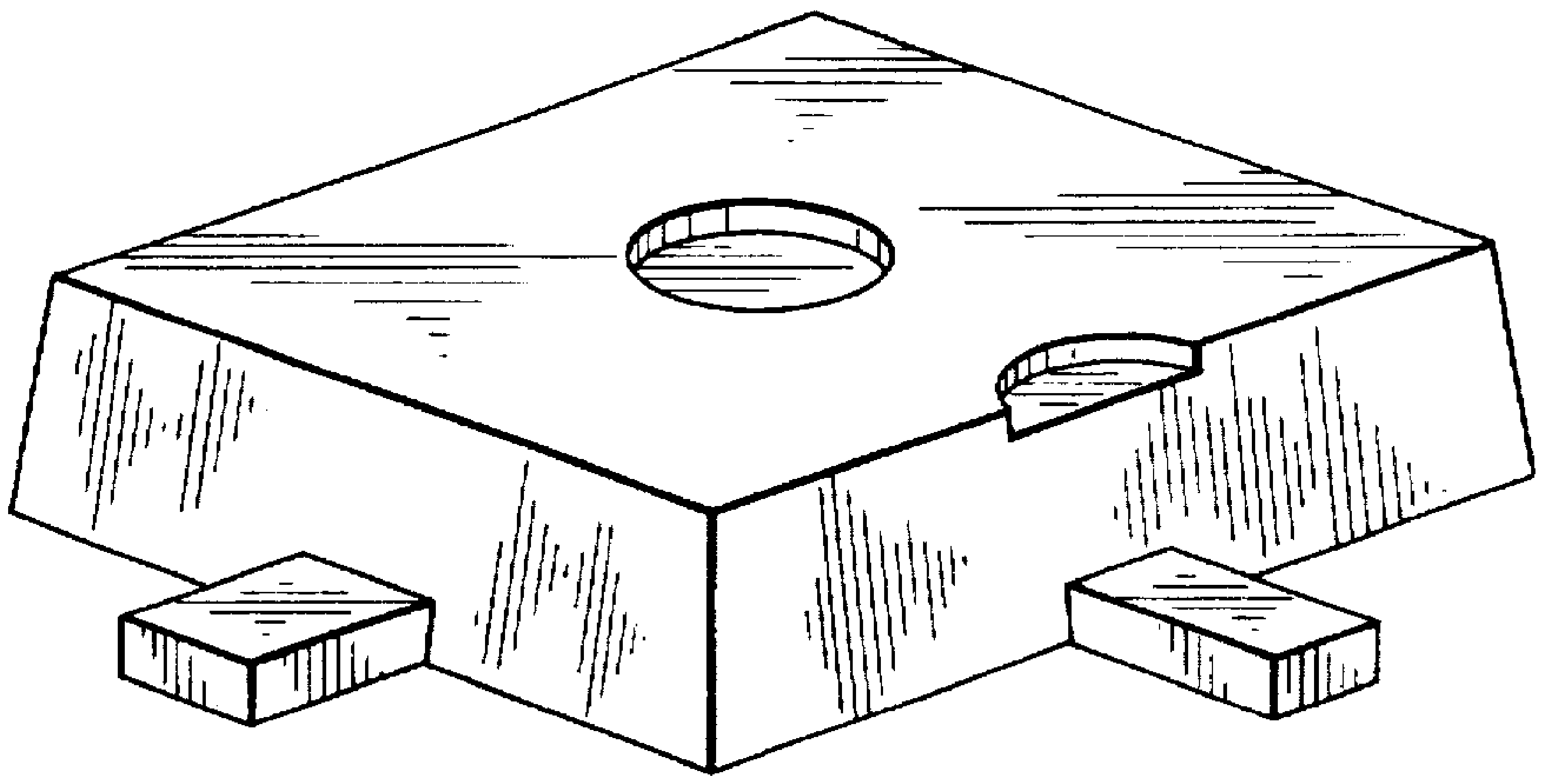
FIG. 5 is a left side elevational view thereof;

FIG. 6 is a right side elevational view thereof;

FIG. 7 is a rear elevational view thereof; and,

FIG. 8 is a bottom plan view thereof.

1 Claim, 3 Drawing Sheets



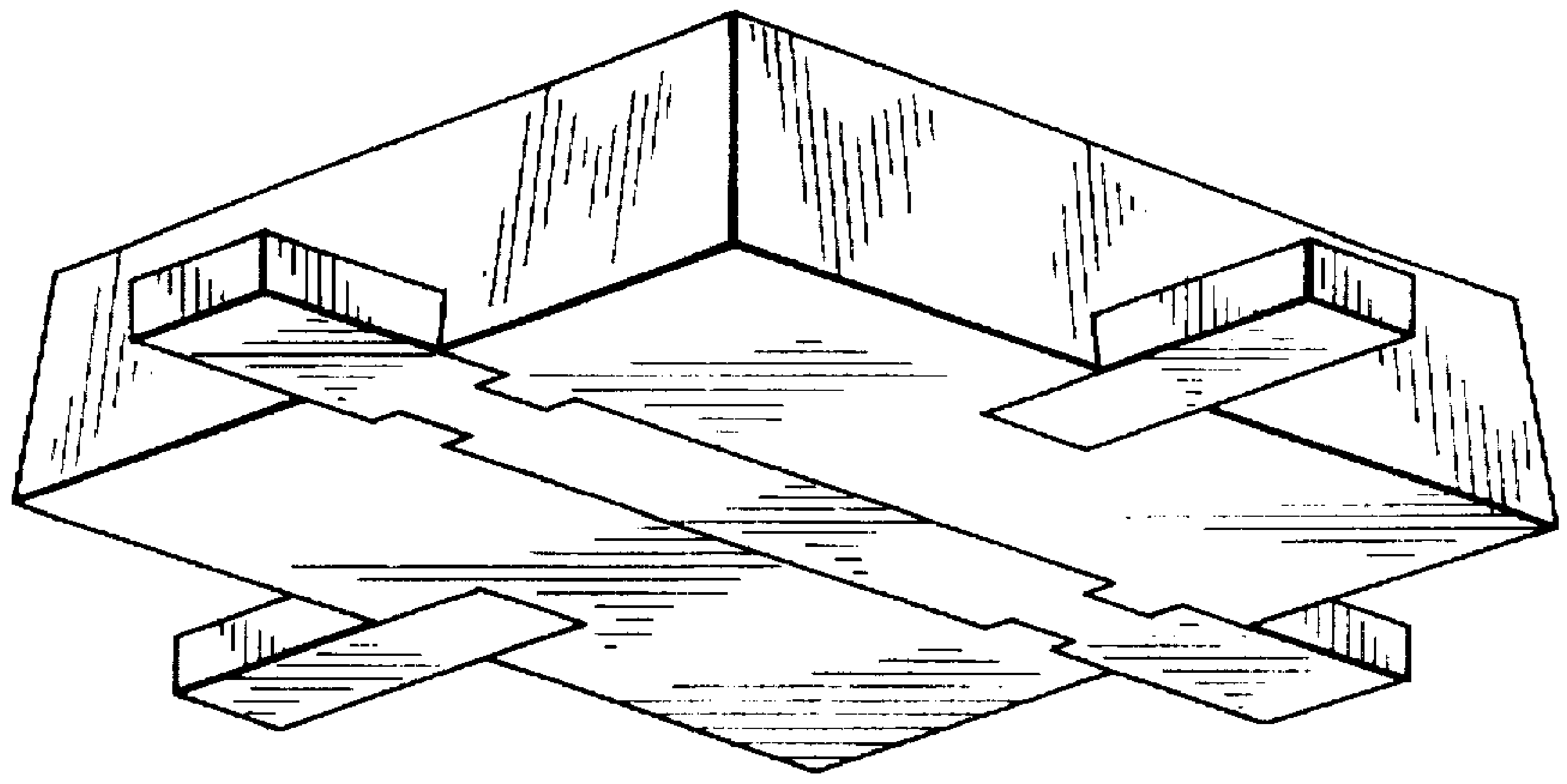


FIG. 1

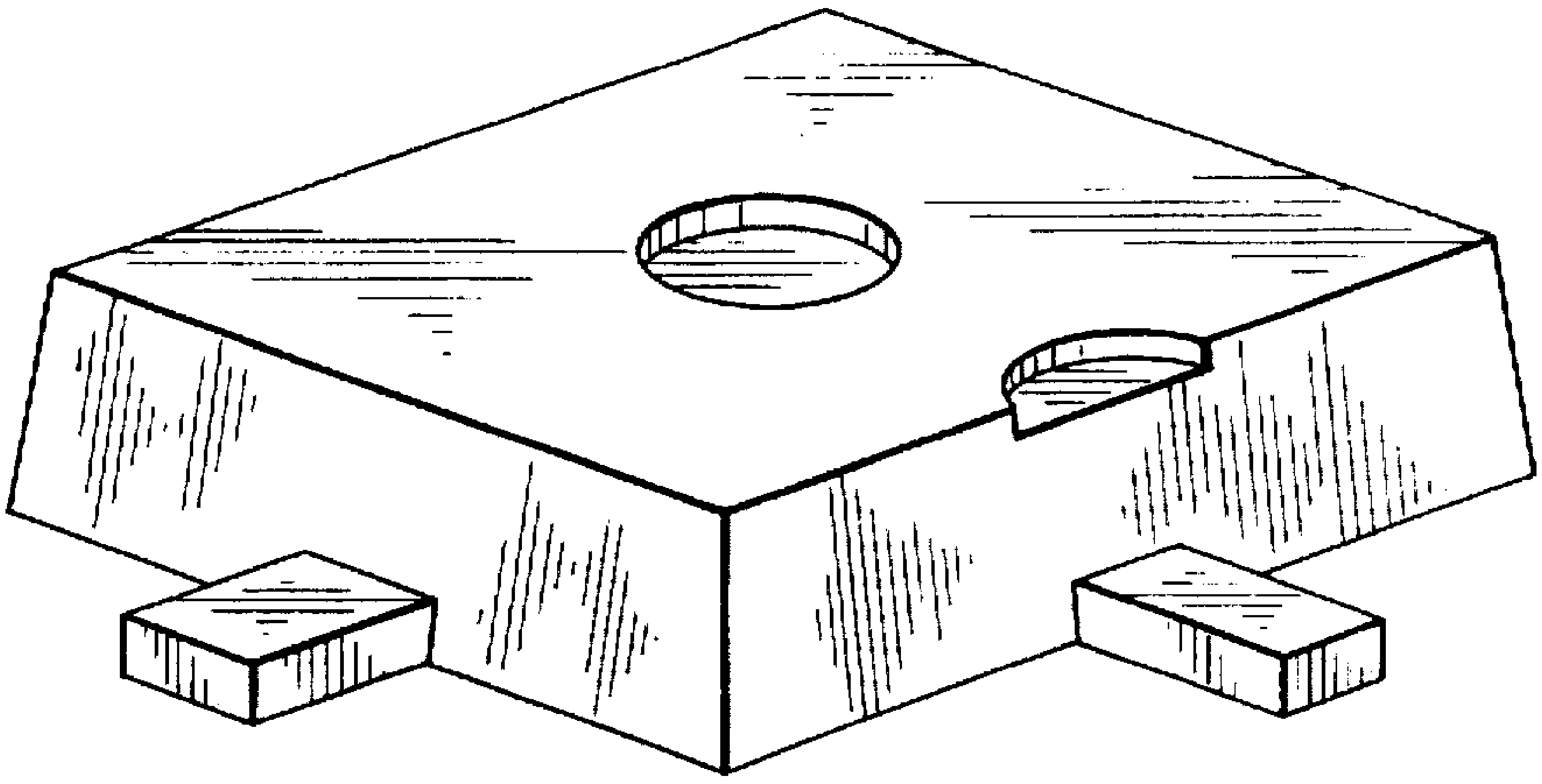


FIG. 2

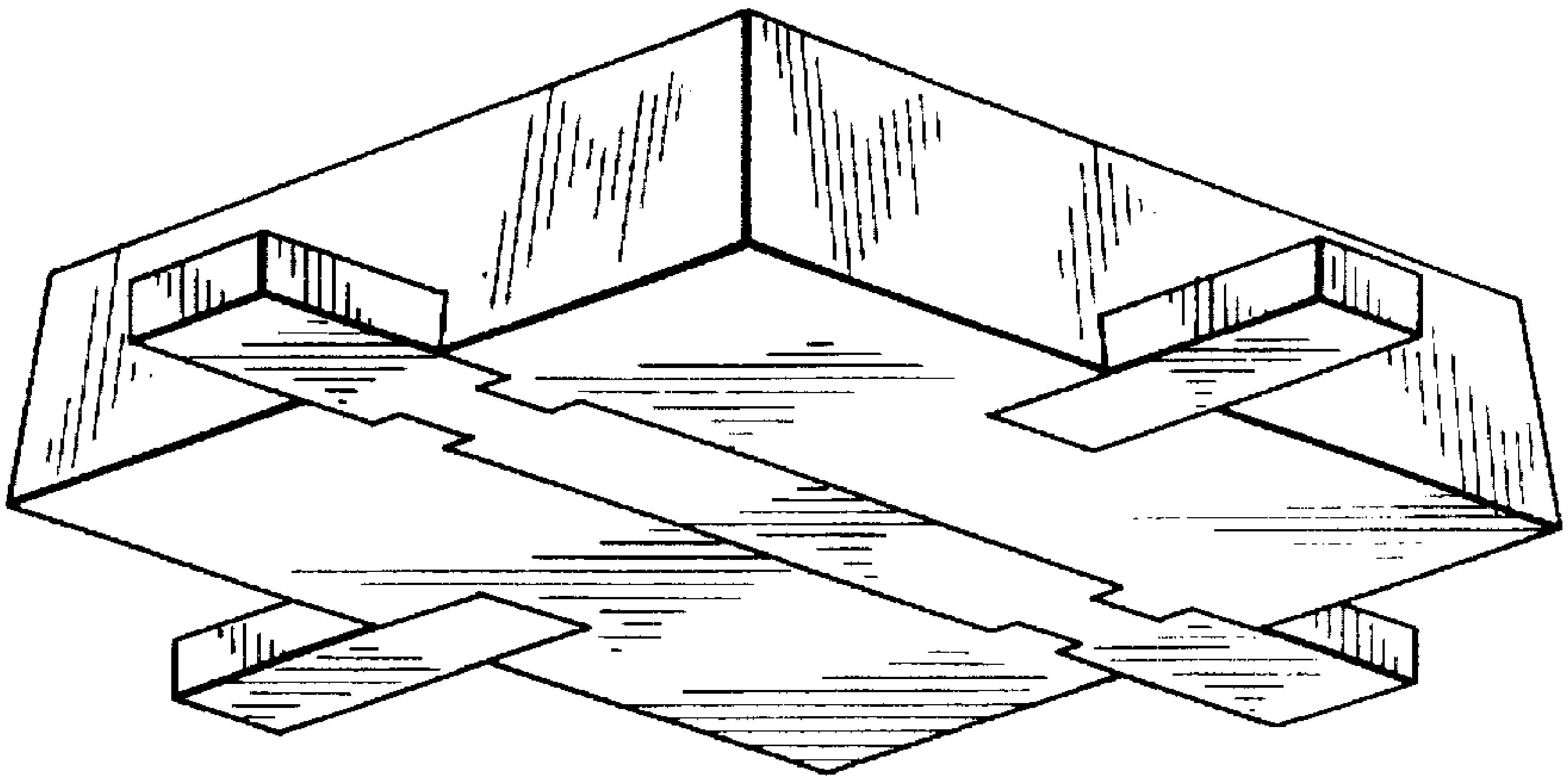


FIG. 3

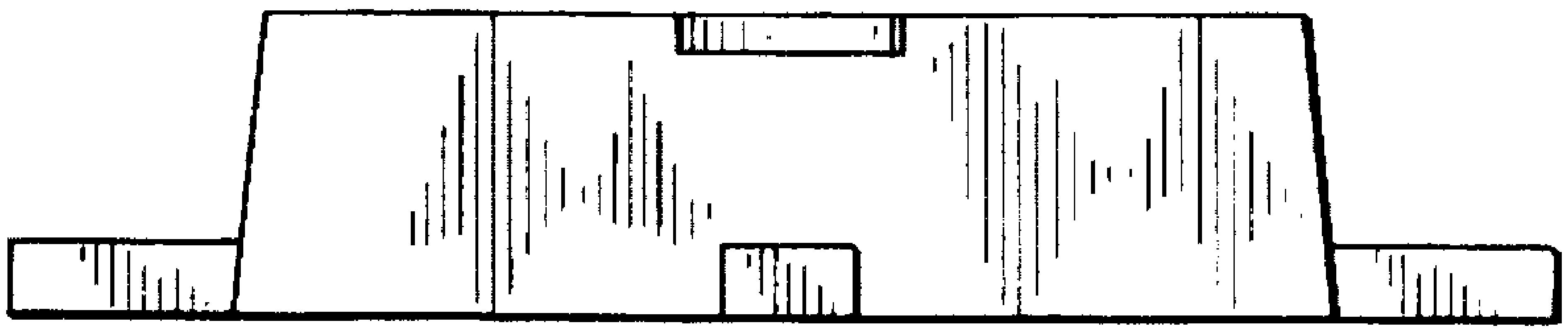


FIG. 4

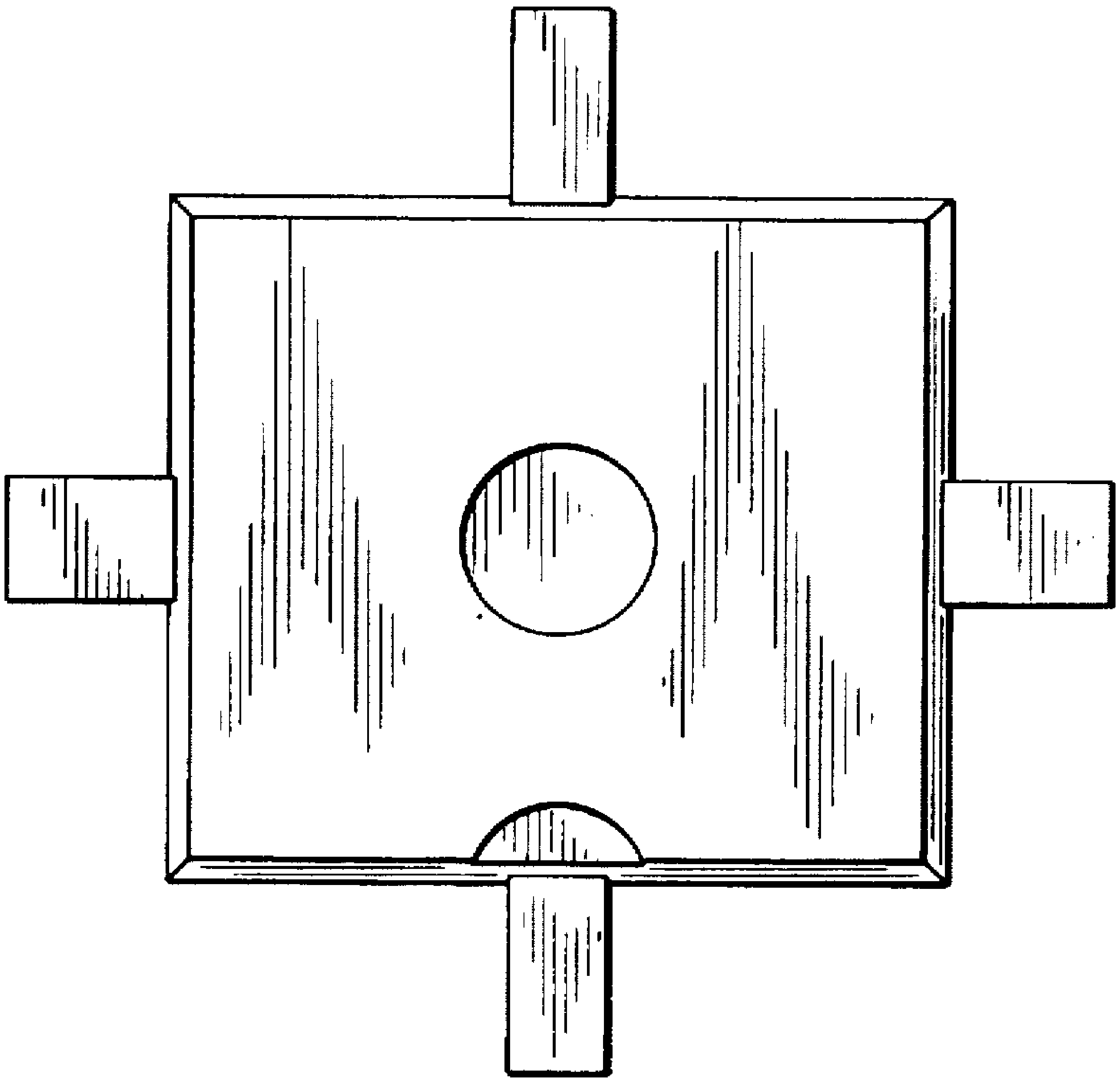


FIG. 5

FIG. 6

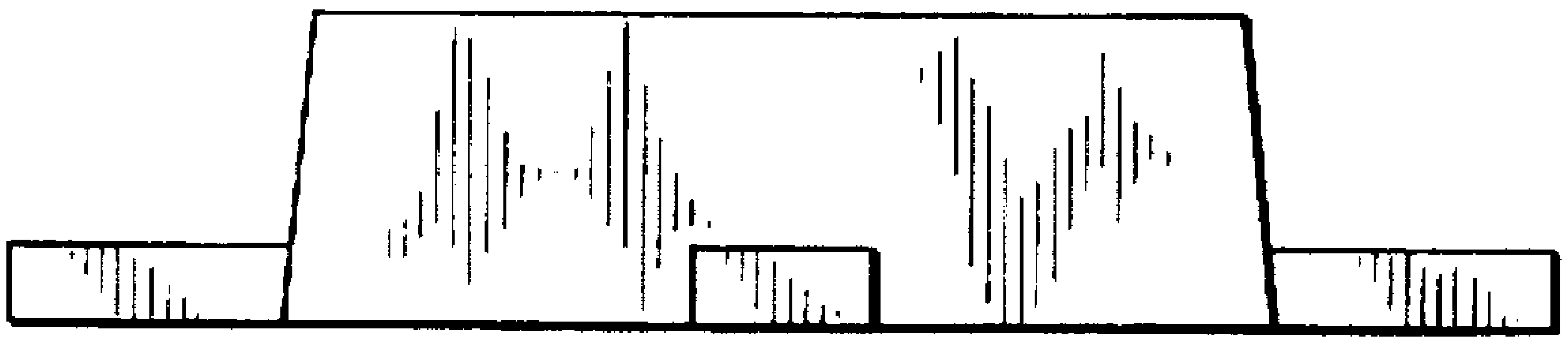


FIG. 7

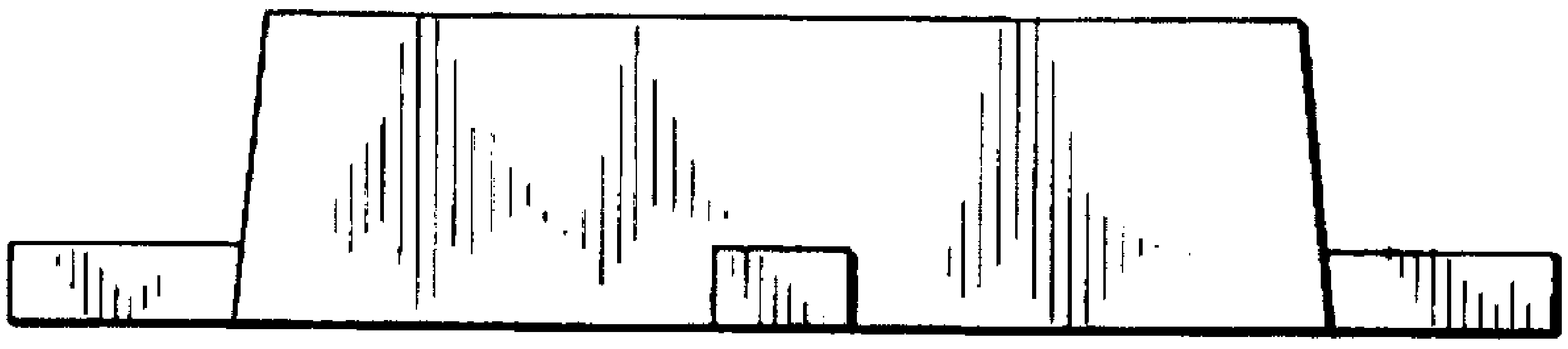


FIG. 8